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January 2014

FDD1600N10ALZ

N-Channel PowerTrench® MOSFET 100 V, 6.8 A, 160 m Ω

Features

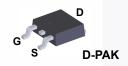
- $R_{DS(on)}$ = 124 m Ω (Typ.) @ V_{GS} = 10 V, I_D = 3.4 A
- $R_{DS(on)} = 175 \text{ m}\Omega \text{ (Typ.)} @ V_{GS} = 5 \text{ V, } I_D = 2.1 \text{ A}$
- Low Gate Charge (Typ.2.78 nC)
- Low C_{rss} (Typ. 2.04 pF)
- · Fast Switching
- · 100% Avalanche Tested
- · Improved dv/dt Capability
- · RoHS Compliant

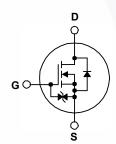
Description

This N-Channel MOSFET is produced using Fairchld Semiconductor's advanced PowerTrench® process that has been tailored to minimize the on-state resistance and maintain superior switching performance.

Application

- · Consumer Appliances
- · LED TV and Monitor
- · Synchronous Rectification
- · Uninterruptible Power Supply
- · Micro Solar Inverter





MOSFET Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol		Parameter		FDD1600N10ALZ	Unit
V _{DSS}	Drain to Source Voltage		100	V	
V _{GSS}	Gate to Source Voltage			±20	V
	Drain Current	- Continuous (T _C = 25°C))	6.8	А
ID	Drain Current	- Continuous (T _C = 100°C	C)	4.3	A
I _{DM}	Drain Current	Current - Pulsed (Note 1)		13.6	Α
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		5.08	mJ	
dv/dt	Peak Diode Recovery dv/o	it	(Note 3)	6.0	V/ns
D	Dower Dissipation	(T _C = 25°C)		14.9	W
P_{D}	Power Dissipation	- Derate Above 25°C		0.12	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range			-55 to +150	°C
TL	Maximum Lead Temperat	ure for Soldering, 1/8" from Case	e for 5 Seconds	300	°C

Thermal Characteristics

Symbol	Parameter FDD1600N10ALZ		Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	8.4	°C/W
R _{0,IA}	Thermal Resistance, Junction to Ambient, Max.	87	-0/00

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FDD1600N10ALZ	1600N10ALZ	DPAK	Tape and Reel	330 mm	16 mm	2500 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100	-	-	V
ΔBV _{DSS} / ΔΤ _J	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C	-	0.1	-	V/°C
1	Zero Gate Voltage Drain Current	V _{DS} = 80 V, V _{GS} = 0 V	-	-	1	
DSS	Zero Gate Voltage Drain Current	$V_{DS} = 80 \text{ V}, V_{GS} = 0 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	-	500	μА
I _{GSS}	Gate to Source Leakage Current	V _{GS} = ±20 V, V _{DS} = 0 V	-	-	±10	μΑ

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu\text{A}$	1.4	-	2.8	V
P	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 3.4 \text{ A}$	-	124	160	mΩ
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 5 V, I _D = 2.1 A	-	175	375	11122
9 _{FS}	Forward Transconductance	V _{DS} = 10 V, I _D = 6.8 A	-	19.6	-	S

Dynamic Characteristics

•							
C _{iss}	Input Capacitance	V - 50 V V	- 0.1/	-	169	225	pF
Coss	Output Capacitance	$V_{DS} = 50 \text{ V}, V_{GS}$ f = 1 MHz	= U V,	-\	43	55	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 1011 12		- \	2.04	-	pF
C _{oss(er)}	Energy Related Output Capacitance	V _{DS} = 50 V, V _{GS}	= 0 V	1	85	-	pF
Q _{g(tot)}	Total Gate Charge at 10V	V _{GS} = 10 V	V _{DD} = 50 V,	-	2.78	3.61	nC
Q _{g(tot)}	Total Gate Charge at 5V	V _{GS} = 5 V	I _D = 6.8 A		1.5	1.95	nC
Q _{gs}	Gate to Source Gate Charge			-	0.72	-	nC
Q_{gd}	Gate to Drain "Miller" Charge			-	0.56	-	nC
V _{plateau}	Gate Plateau Volatge		(Note 4)	-	4.02	-	V
Q _{sync}	Total Gate Charge Sync.	$V_{DS} = 0 \text{ V}, I_{D} = 3$.4 A	- /	2.5	-	nC
Q _{oss}	Output Charge	V_{DS} = 50 V, V_{GS}	= 0 V	- /	5.2	-	nC
ESR	Equivalent Series Resistance (G-S)	f = 1 MHz		-/	2.1	-	Ω

Switching Characteristics

_							
t _{d(on)}	Turn-On Delay Time			-	7	24	ns
t _r	Turn-On Rise Time	$V_{DD} = 50 \text{ V}, I_{D} = 6.8 \text{ A},$		-	2	14	ns
t _{d(off)}	Turn-Off Delay Time	V_{GS} = 10 V, R_{G} = 4.7 Ω		-	13	36	ns
t _f	Turn-Off Fall Time		(Note 4)	-	2	14	ns

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain to Source Diode Forward Current		-		6.8	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	13.6	Α
V_{SD}	Drain to Source Diode Forward Voltage V _{GS} =	O V, I _{SD} = 6.8 A	-	-	1.3	V
t _{rr}	Reverse Recovery Time V _{GS} =	O V, I _{SD} = 6.8 A, V _{DS} = 50 V,	-	37	-	ns
Q _{rr}	Reverse Recovery Charge dI _F /dt =	: 100 A/μs	-	42	-	nC

Notes

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2. L = 1 mH, I_{AS} =3.18 A, R_{G} = 25 Ω , starting T_{J} = 25°C.
- 3. $I_{SD} \le 6.8$ A, di/dt ≤ 200 A/ μ s, $V_{DD} \le BV_{DSS}$, starting T_J = 25°C.
- 4. Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

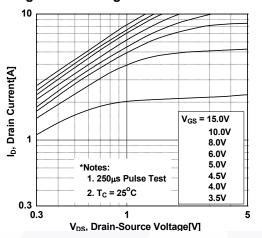


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

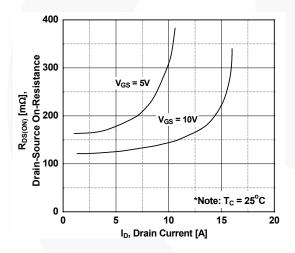


Figure 5. Capacitance Characteristics

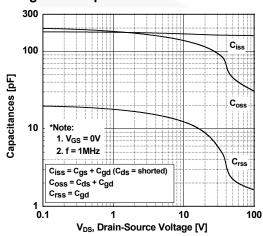


Figure 2. Transfer Characteristics

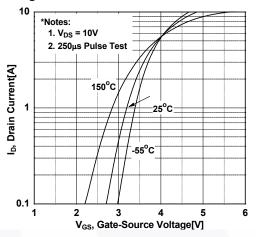


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

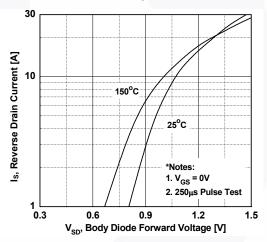
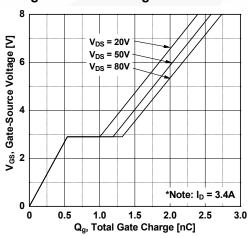


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

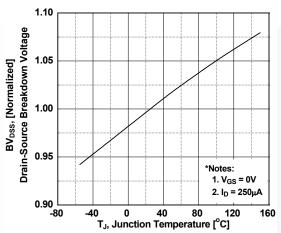


Figure 9. Maximum Safe Operating Area

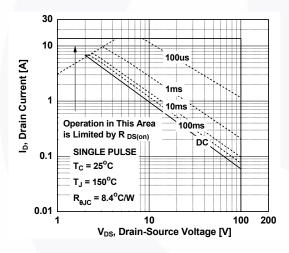


Figure 11. Eoss vs. Drain to Source Voltage

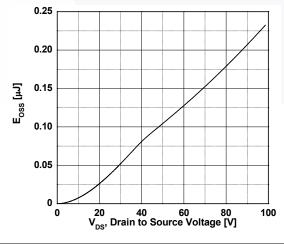


Figure 8. On-Resistance Variation vs. Temperature

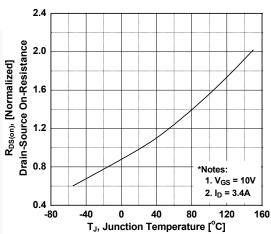


Figure 10. Maximum Drain Current vs. Case Temperature

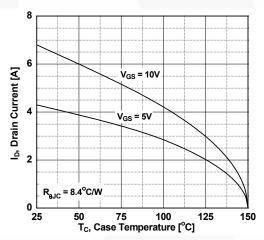
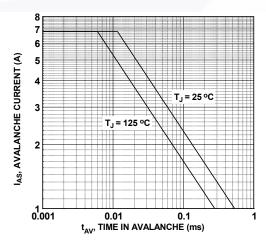
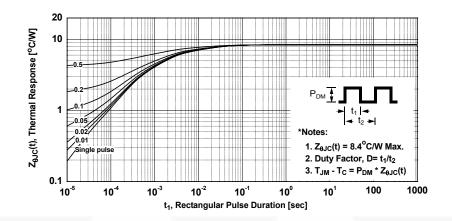


Figure 12. Unclamped Inductive Switching Capability



Typical Performance Characteristics (Continued)

Figure 13. Transient Thermal Response Curve



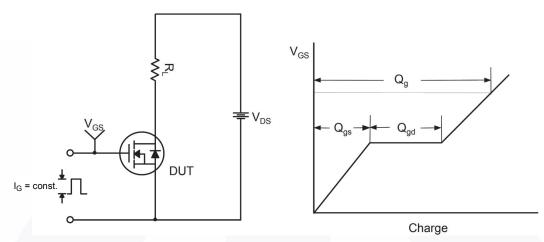


Figure 14. Gate Charge Test Circuit & Waveform

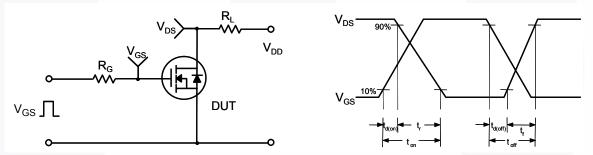


Figure 15. Resistive Switching Test Circuit & Waveforms

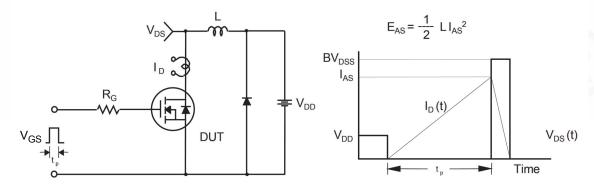


Figure 16. Unclamped Inductive Switching Test Circuit & Waveforms

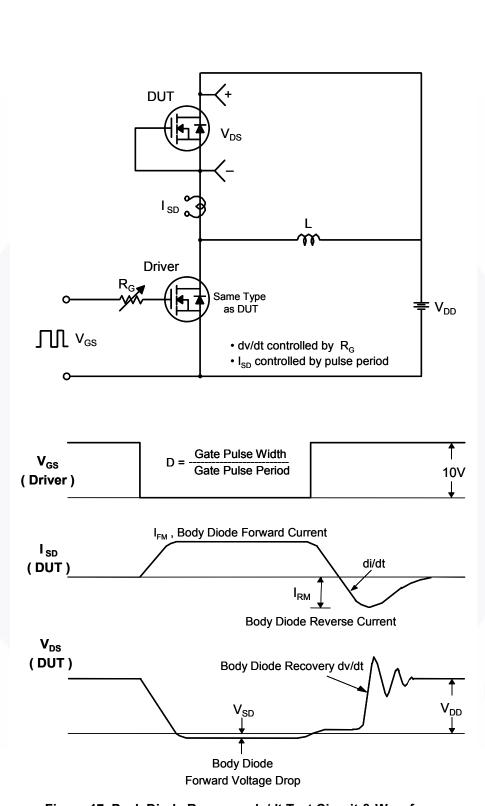


Figure 17. Peak Diode Recovery dv/dt Test Circuit & Waveforms

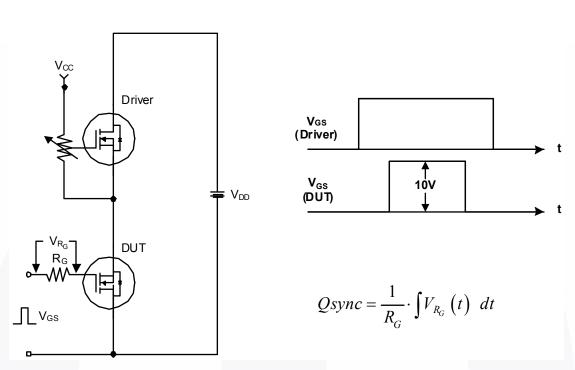


Figure 18. Total Gate Charge Qsync. Test Circuit & Waveforms

Mechanical Dimensions -5.55 MIN-1.27 6.22 5.97 6.50 MIN 1.02 MAX C 2 (0.59)0.89 2.29 ⊕ 0.25 A A C 4.57 LAND PATTERN RECOMMENDATION SFF 2.18 4.32 MIN NOTE D 0.58 0.45 5.21 MIN 10.41 9.40 SFF DFTAIL A ○ 0.10 B

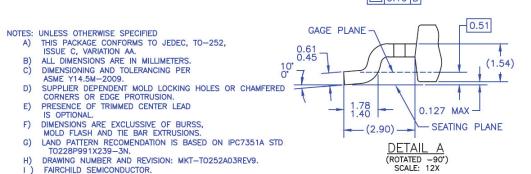


Figure 19. TO252 (D-PAK), Molded, 3-Lead, Option AA&AB

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